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Subject Code:- AMTVL0112

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NOIDA INSTITUTE OF ENGINEERING AND TECHNOLOGY, GREATER NOIDA

(An Autonomous Institute Affiliated to AKTU, Lucknow)

M.Tech

SEM: I - THEORY EXAMINATION (2022 - 2023)

Subject: MOS Device Modeling

Time: 3 Hours

Max. Marks: 70

General Instructions:

IMP: Verify that you have received the question paper with the correct course, code, branch etc.

- 1. This Question paper comprises of three Sections -A, B, & C. It consists of Multiple Choice Questions (MCQ's) & Subjective type questions.**
- 2. Maximum marks for each question are indicated on right -hand side of each question.**
- 3. Illustrate your answers with neat sketches wherever necessary.**
- 4. Assume suitable data if necessary.**
- 5. Preferably, write the answers in sequential order.**
- 6. No sheet should be left blank. Any written material after a blank sheet will not be evaluated/checked.**

SECTION A

15

1. Attempt all parts:-

- | | | |
|------|--|---|
| 1-a. | The majority carriers of p-type semiconductor are (CO1) | 1 |
| | (a) Holes | |
| | (b) Positive ions | |
| | (c) Electrons | |
| | (d) Negative ions | |
| 1-b. | Gate capacitance per unit area is scaled by (CO2) | 1 |
| | (a) α | |
| | (b) 1 | |
| | (c) $1/\beta$ | |
| | (d) β | |
| 1-c. | The junction parasitic capacitance are produced due to _____ (CO3) | 1 |
| | (a) Source diffusion regions | |
| | (b) Gate diffusion regions | |
| | (c) Drain diffusion region | |

	(d) All of the mentioned	
1-d.	Types of SOI Devices are (CO4)	1
	(a) PASOI and FASOI	
	(b) PESOI and FESOI	
	(c) PDSOI and FDSOI	
	(d) None of the above	
1-e.	Hot carrier degradation phenomena occur in (CO5)	1
	(a) advanced BJTs	
	(b) Diodes	
	(c) simple BJTs	
	(d) CMOS	

2. Attempt all parts:-

2.a.	Compare NMOS and PMOS. (CO1)	2
2.b.	Draw the transfer characteristic for n-channel depletion type MOSFET? (CO2)	2
2.c.	Draw the small signal equivalent model of a MOSFET, What does gm V_{GS} stand for? (CO3)	2
2.d.	Explain the term Fin in FinFET. (CO4)	2
2.e.	What is the advantage of SPICE modeling of MOS Transistor ? (CO5)	2

SECTION B

20

3. Answer any five of the following:-

3-a.	Explain the operation of MOS under bias condition. (CO1)	4
3-b.	List out characteristics of Non ideal MOSFET. (CO1)	4
3-c.	A MOSFET is to operate at $ID = 0.1$ mA and is to have $gm = 1$ mA/V. If $k_n' = 50 \mu A/V^2$, find the required W/L ratio and the overdrive voltage. (CO2)	4
3-d.	Explain the terms single stage MOS amplifier and MOSFET internal capacitances.(CO2)	4
3.e.	Draw low-frequency small-signal equivalent circuit model of NMOS. (CO3)	4
3.f.	Compare kink effect in FDSOI and PDSOI devices.(CO4)	4
3.g.	What are the variation of mobility with electric field is observed in level-2 model? (CO5)	4

SECTION C

35

4. Answer any one of the following:-

4-a. Sketch the energy band diagrams of an MOS capacitor with N-type silicon substrate and N+ poly-Si gate at flatband, in accumulation, in depletion, at threshold, and in inversion. (CO1) 7

4-b. What are the types of oxide charges? Explain in detail.(CO1) 7

5. Answer any one of the following:-

5-a. Discuss the frequency response of MOSFET CS amplifier.(CO2) 7

5-b. Describe the channel length modulation effect and define the parameter λ .
Describe the body effect and define the gama parameter. (CO2) 7

6. Answer any one of the following:-

6-a. Explain and draw high-frequency small-signal equivalent circuit model of PMOS. (CO3) 7

6-b. What is sub threshold swing? Explain the effect of interface states on sub threshold swing in details. (CO3) 7

7. Answer any one of the following:-

7-a. Explain the advantages and disadvantages of FinFET over the planer MOSFET. (CO4) 7

7-b. Explain the construction, working and characteristics of FinFET devices. (CO4) 7

8. Answer any one of the following:-

8-a. What are the small geometry corrections in level-2 ? (CO5) 7

8-b. What is BSIM? Explain in detail. (CO5) 7